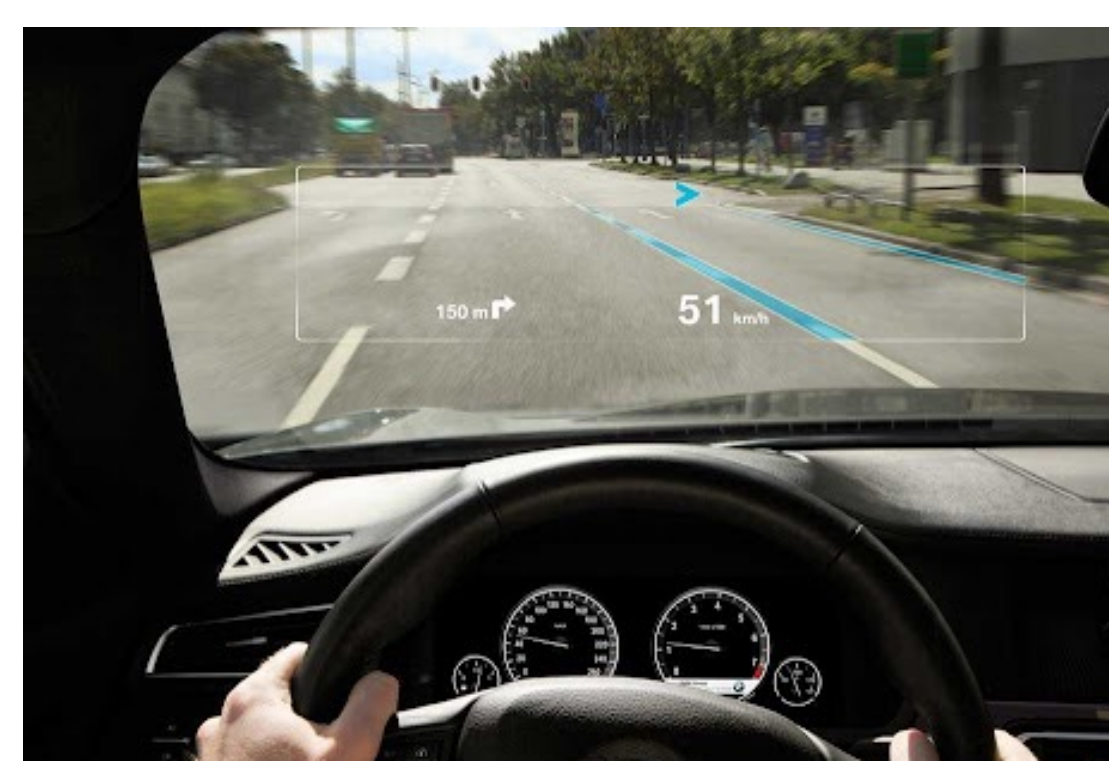
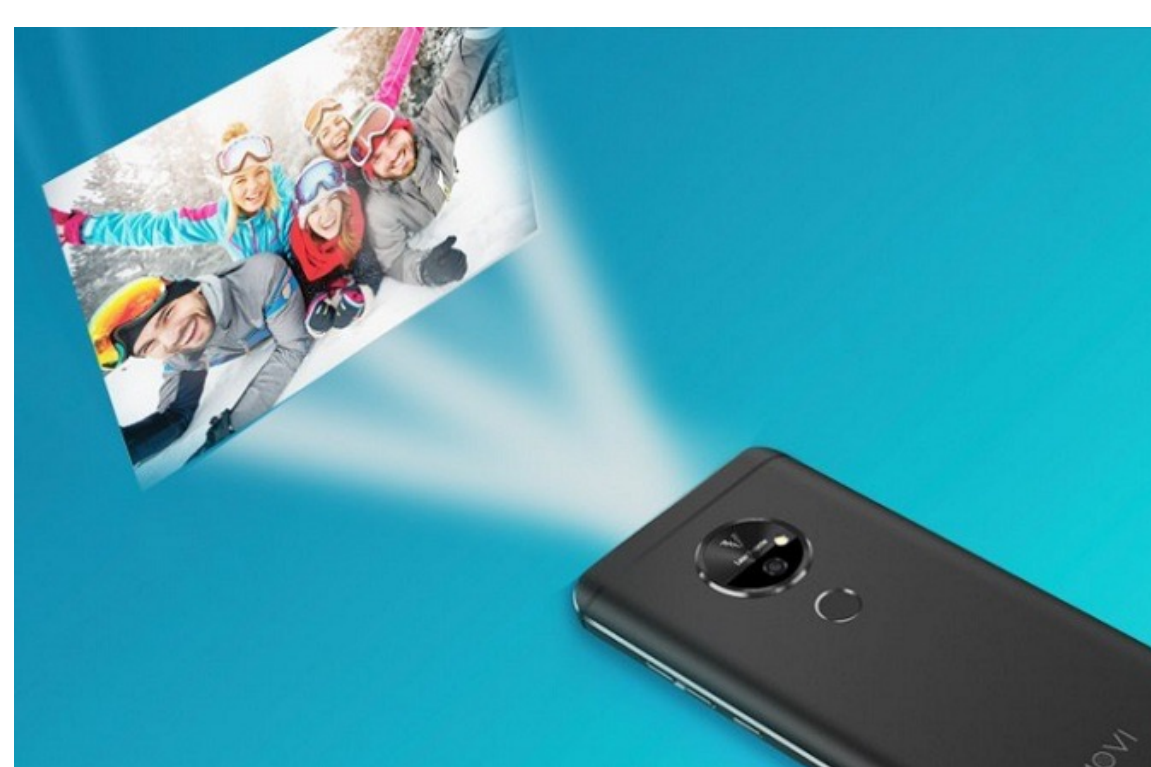


In this work, we report on the fabrication and testing of a novel integrated detector for visible wavelength range that is based on the well-known photoconductive properties of amorphous Silicon (a-Si). The device is realized on top of  $\text{Si}_3\text{N}_4$  core waveguides by etching a sub-millimetric trench in the cladding and depositing the a-Si inside of it, with a specific pattern for interaction reduction. A responsivity of 10 mA/W and a sensitivity of -45 dBm have been demonstrated.

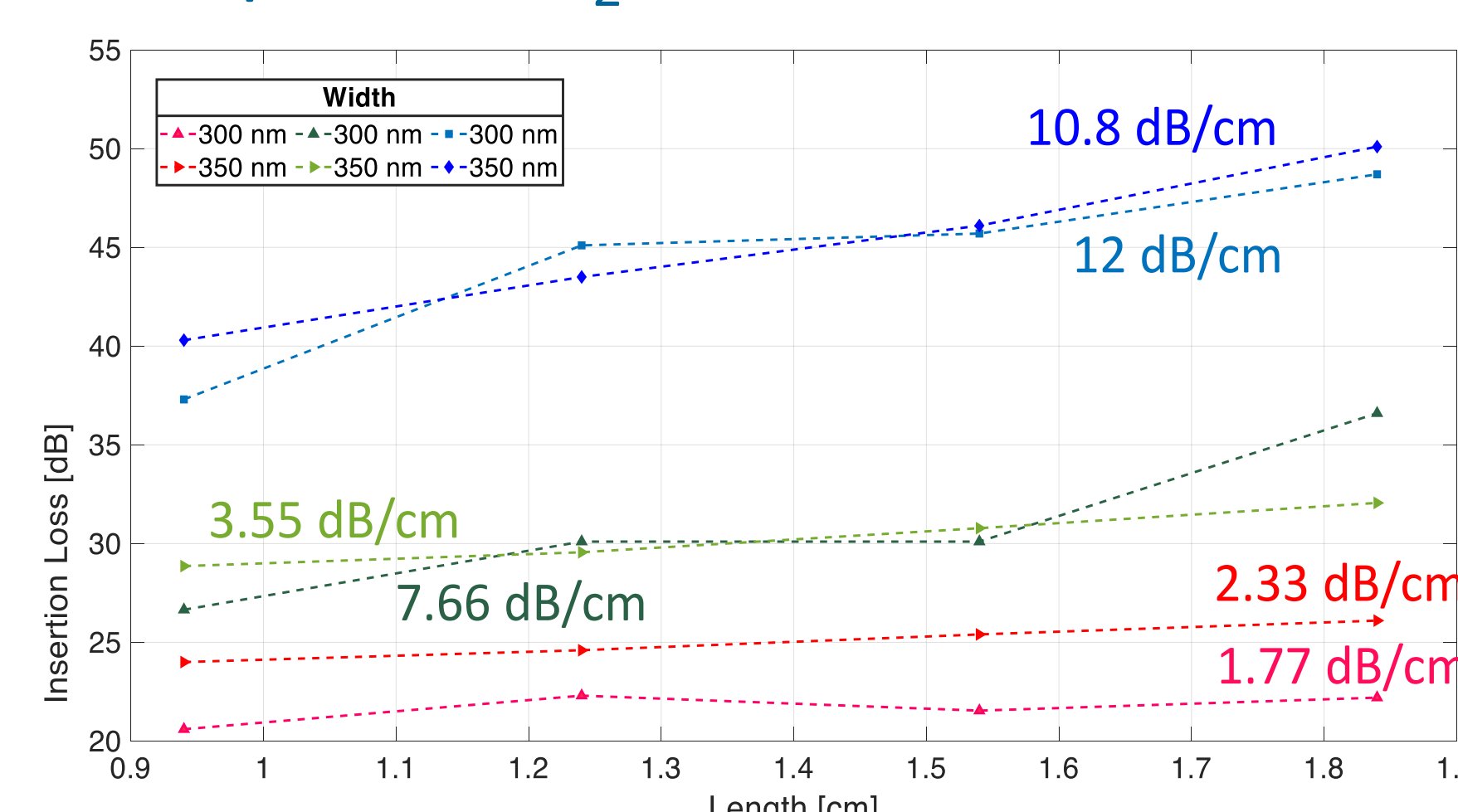
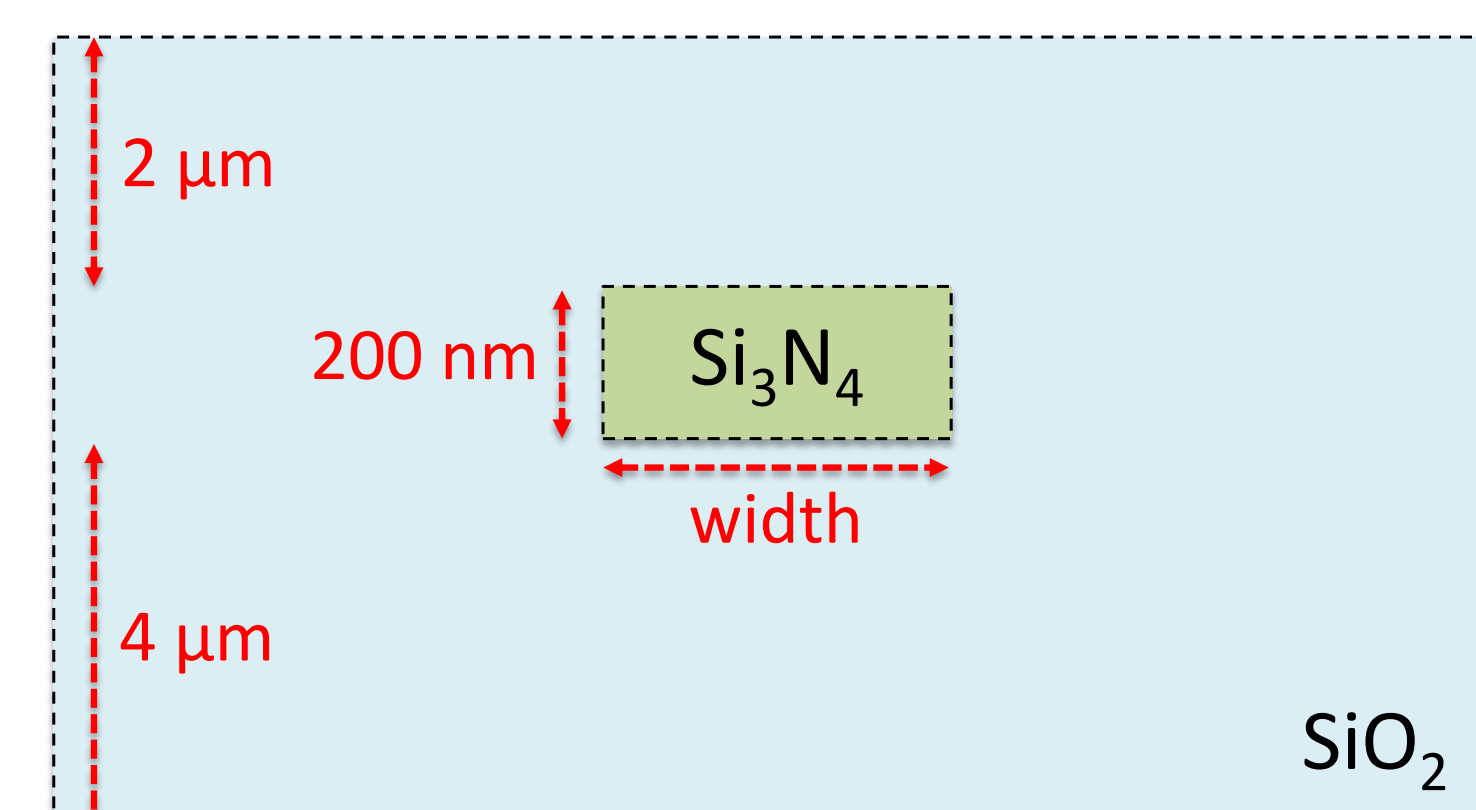
## The visible wavelength range

- Integration of various photonic components on a single chip, including light sources and detectors, is a critical route toward the realization of dense photonic integrated circuits (PICs). These are of interest not only for traditional applications in data and telecommunications but also for applications in imaging, metrology, biosensing, nanomedicine, and quantum optics which typically require operation in the visible wavelength range.
- Many companies and university are now working in this wavelength range, with a particular focus on the 630, 520 and 450 nm wavelengths (RGB): University of Fukui (JP)<sup>1</sup> presented a device measuring  $8 \times 4 \times 3$  mm able to project a  $1280 \times 720$  colour video. In this context, an integrated visible detector will help reducing dimension and costs.

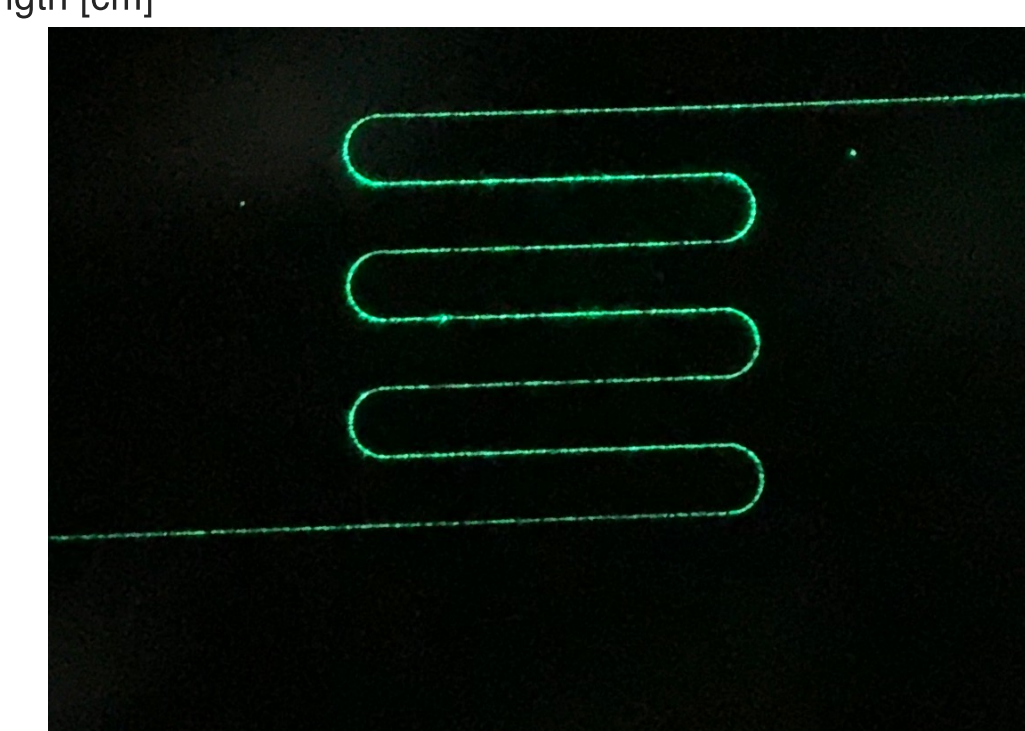
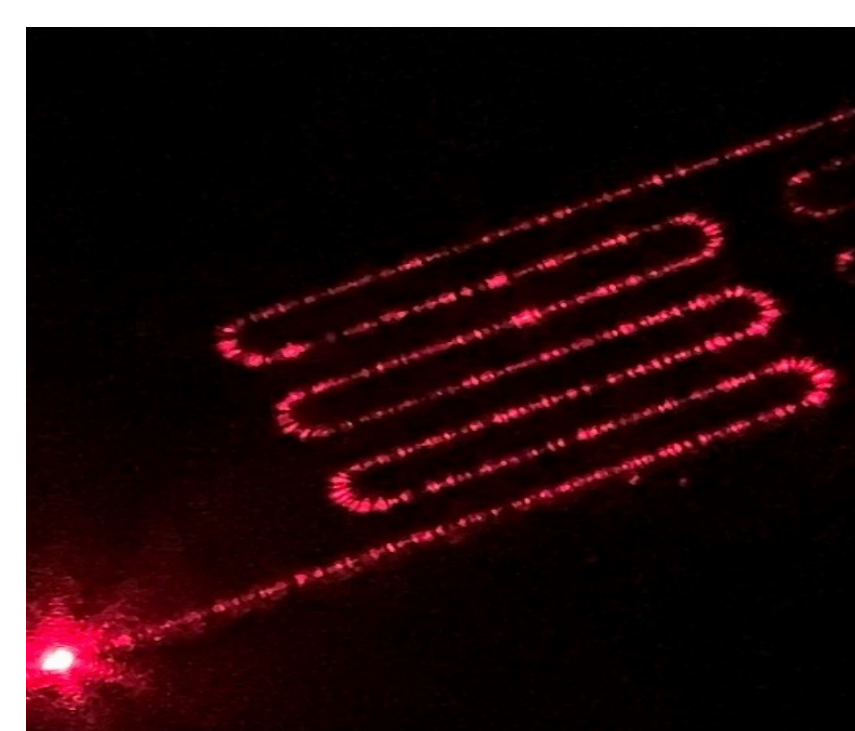


## Visible platform

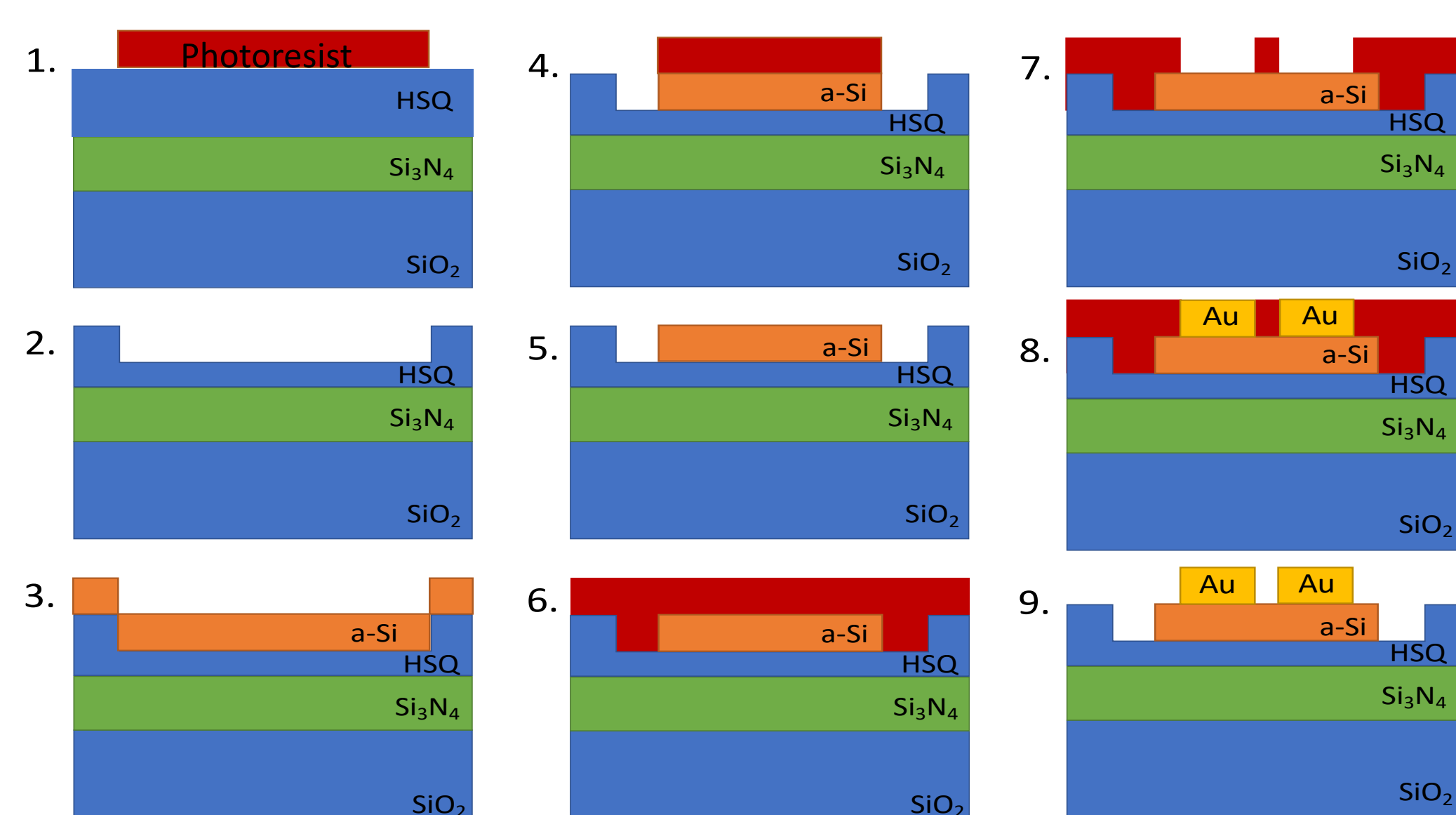
- A  $\text{Si}_3\text{N}_4$  core waveguides is building block we designed and tested for our integrated photonic circuits, consisting in a 200 nm thick  $\text{Si}_3\text{N}_4$  film completely etched till the Bottom Oxide layer and cladded by  $2 \mu\text{m}$  of  $\text{SiO}_2$ .



- The fabricated spirals presented a propagation loss that is comparable with the state of the art<sup>2</sup>: 1.77 dB/cm for 660 nm, 3.55 dB/cm for 520 nm and 10 dB/cm for blue



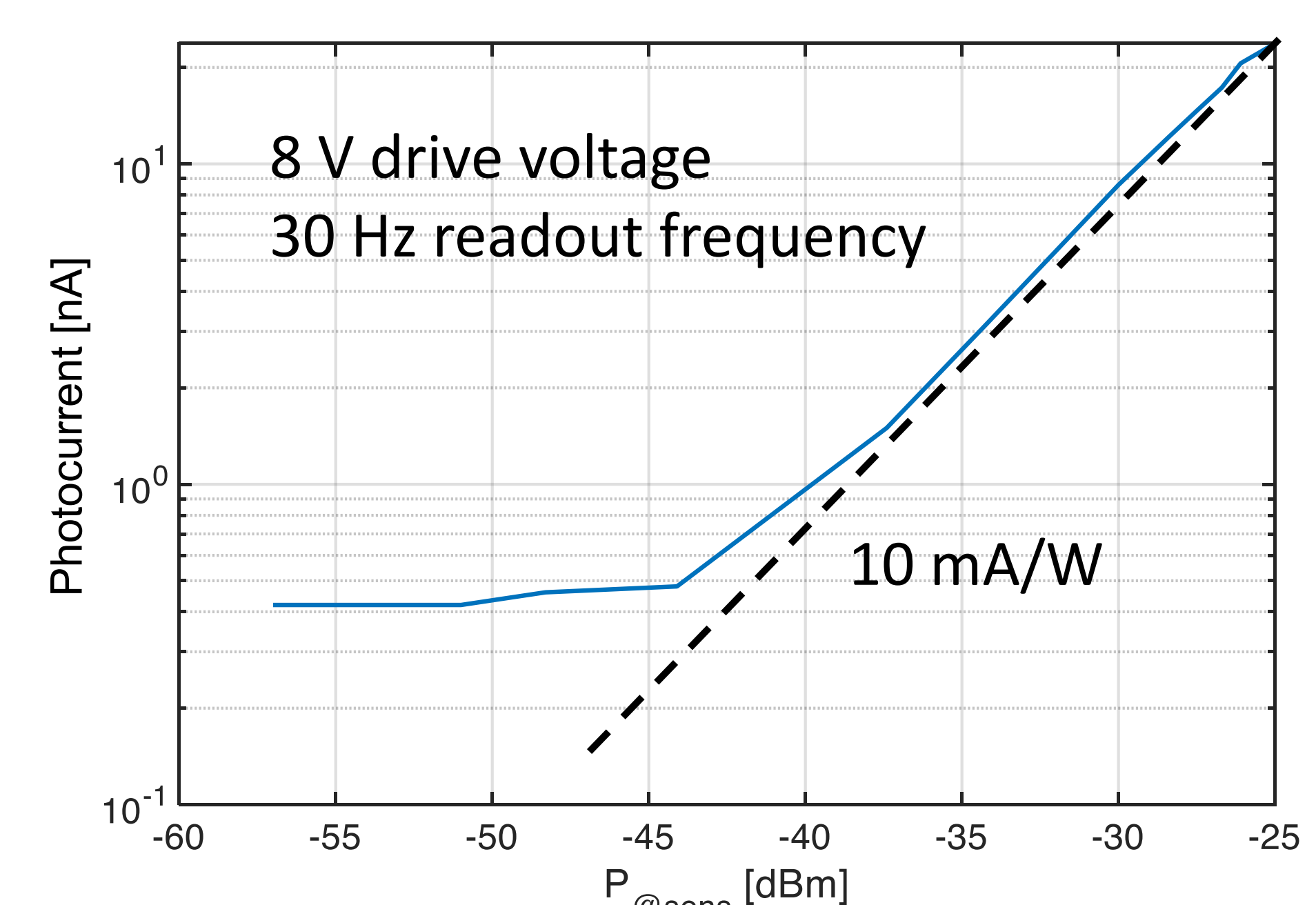
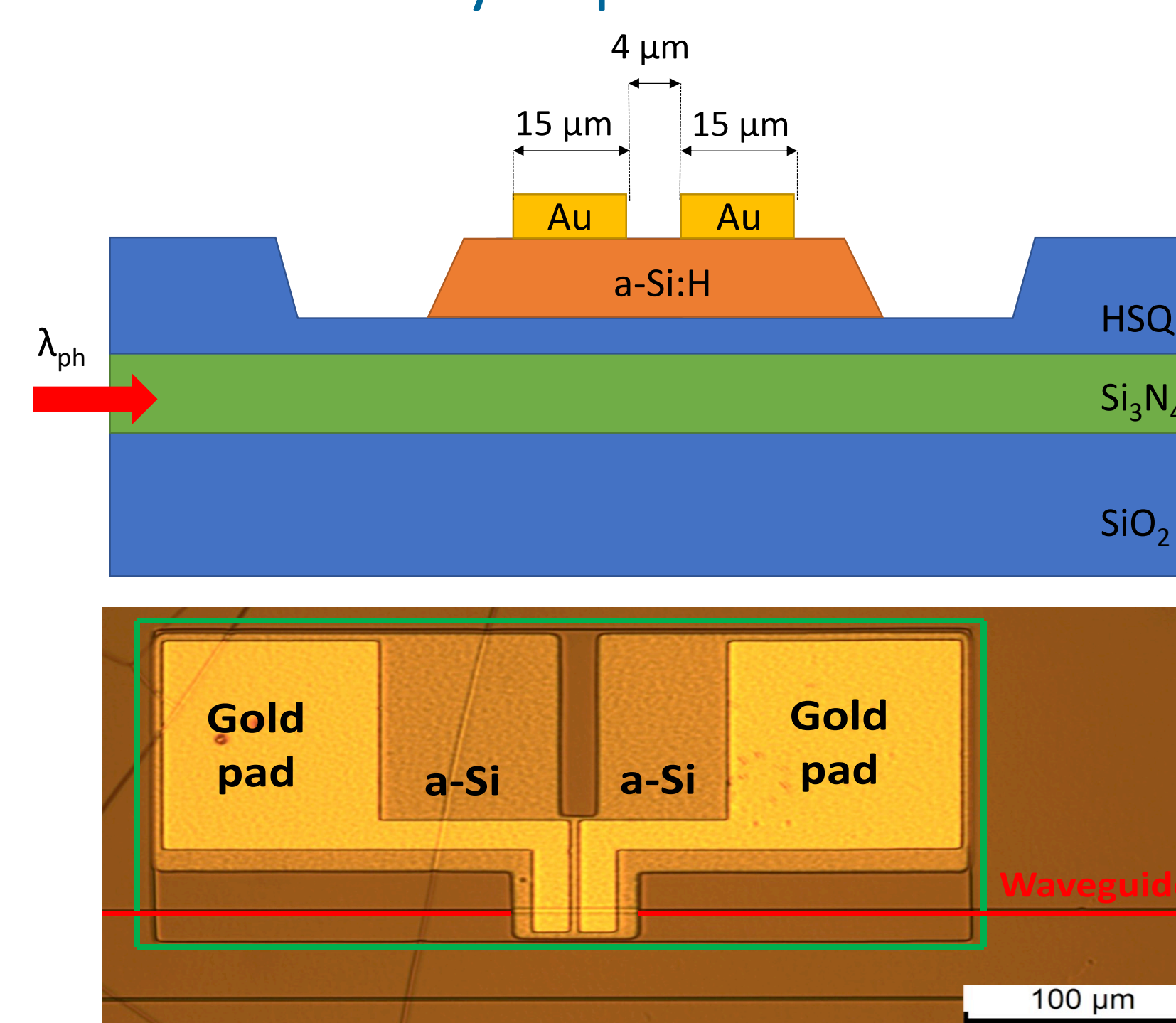
## Fabrication process flow



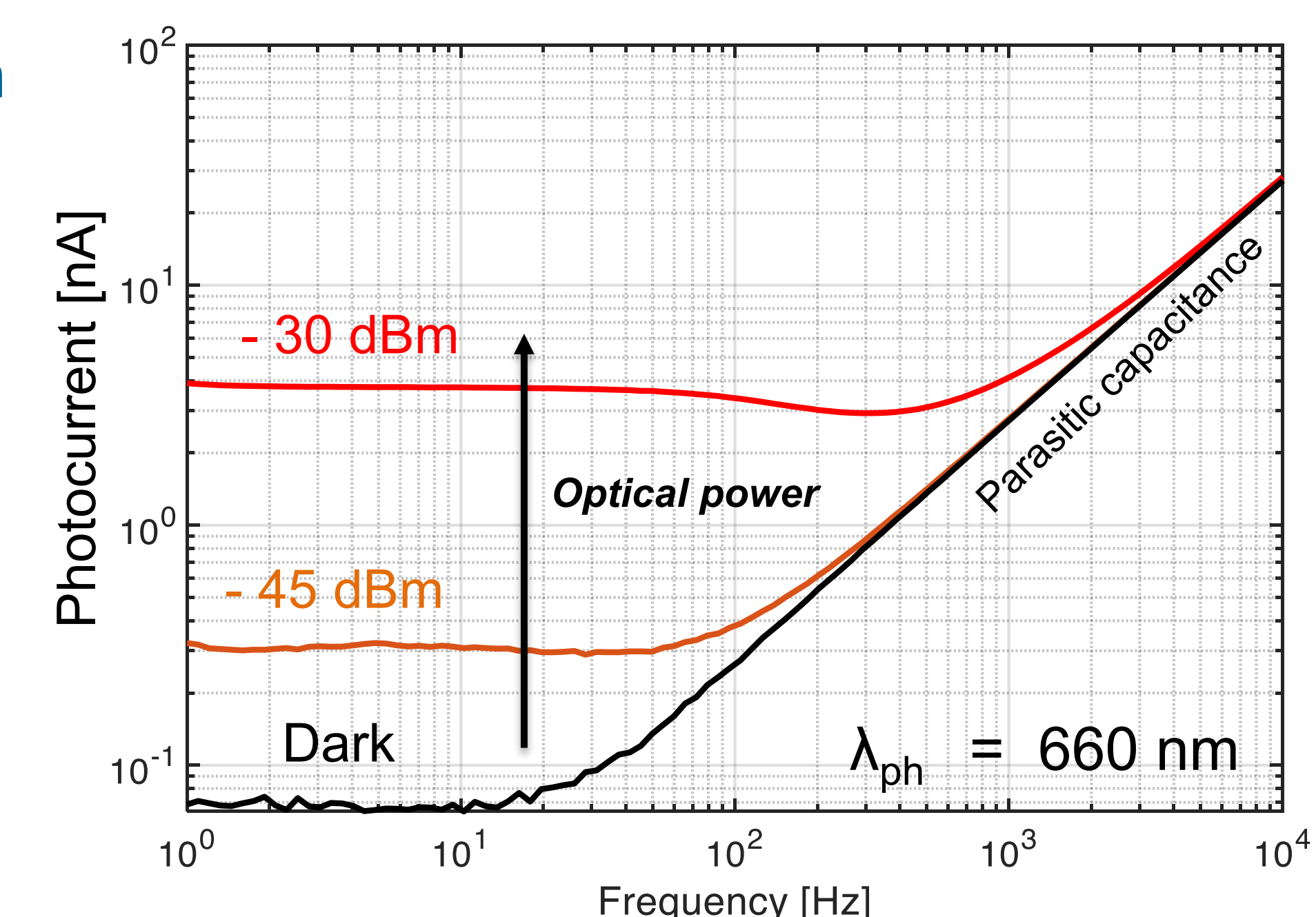
- Cladding thinning by Direct writing lithography and reactive ion etching (1,2)
- Amorphous Silicon (a-Si) deposition by plasma enhanced chemical vapor deposition (3)
- Patterning of a-Si through direct writing lithography and reactive ion etching. This will define the interaction area between the light and the a-Si (4,5).
- The electrical contacts are then made by a final lithography, the deposition of the pads through thermal evaporation and the successive lift-off step (6,7,8).
- The detector is  $34 \mu\text{m}$  long, making it very compact and suitable for any photonic integrated circuit (9).**

## Detector characterization

- The chip is bonded to a PCB, reducing the parasitic capacitance that limits the bandwidth of the detector. A laser diode at  $\lambda = 660 \text{ nm}$ , is edge coupled to the the  $\text{Si}_3\text{N}_4$  core waveguide on chip while the responsivity of the detector is estimated by impedentiometric measurement.



- Photocurrent of  $\sim 4 \text{ nA}$  @  $-30 \text{ dBm}$
- Sensitivity  $-45 \text{ dBm}$  @  $30 \text{ Hz}$
- Bandwidth  $1 \text{ kHz}$  at  $-30 \text{ dBm}$
- Dark current  $65 \text{ pA}$  (@  $8 \text{ V}$ )
- Responsivity  $10 \text{ mA/W}$
- Length  $34 \mu\text{m}$



## References

[1] A. Nakao, S. Yamada, T. Katsuyama, O. Kawasaki, K. Iwabata, K. Horii, and A. Himeno, "Compact Full-color Laser Beam Scanning Image Projector Based on a Waveguide-type RGB Combiner", Proceedings of the International Display Workshops, p. 649, Dec. 2020.

[2] Sacher et al., "Visible-light silicon nitride waveguide devices and implantable neurophotonic probes on thinned 200 mm silicon wafers", Optics Express (Dec. 2019)

## Contact info

Christian De Vita  
christian.devita@polimi.it  
Francesco Morichetti  
francesco.morichetti@polimi.it

